

## SN74LVC32A-Q1 車載用、クワッド、2 入力、正論理 OR ゲート

### 1 特長

- 車載アプリケーション認定済み
- 2V~3.6V で動作
- 5.5V までの入力電圧に対応
- 最大  $t_{pd}$  3.8ns (3.3V 時)
- $V_{OLP}$  標準値 (出力グランド バウンス)  $< 0.8V$  ( $V_{CC} = 3.3V$ 、 $T_A = 25^\circ C$ )
- $V_{OHV}$  標準値 (出力  $V_{OH}$  アンダーシュート)  $> 2V$  ( $V_{CC} = 3.3V$ 、 $T_A = 25^\circ C$ )

### 2 概要

SN74LVC32A-Q1 クワッド 2 入力正論理 OR ゲートは、2.7V~3.6V の  $V_{CC}$  で動作するように設計されています。

これらのデバイスはブール関数  $Y = A + B$  or  $Y = \overline{\overline{A} \cdot \overline{B}}$  を正論理で実行します。

入力は 3.3V または 5V のデバイスから駆動できます。この機能により、3.3V と 5V が混在するシステム環境での変換装置としてこのデバイスを使用できます。

### パッケージ情報

部品番号	パッケージ <sup>(1)</sup>	パッケージサイズ <sup>(2)</sup>	本体サイズ <sup>(3)</sup>
SN74LVC32A-Q1	BQA (WQFN, 14)	3mm × 2.5mm	3mm × 2.5mm
	D (SOIC, 14)	8.65mm × 6mm	8.65mm × 3.9mm
	PW (TSSOP, 14)	5mm × 6.4mm	5mm × 4.4mm

- (1) 詳細については、[セクション 10](#) を参照してください。
- (2) パッケージサイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。
- (3) 本体サイズ (長さ × 幅) は公称値であり、ピンは含まれません。



各ゲートの論理図 (正論理)



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### 3 Pin Configuration and Functions

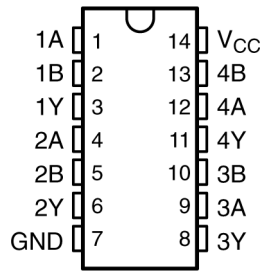


図 3-1.

D or PW Package, 14-Pin SOIC or TSSOP (Top View)

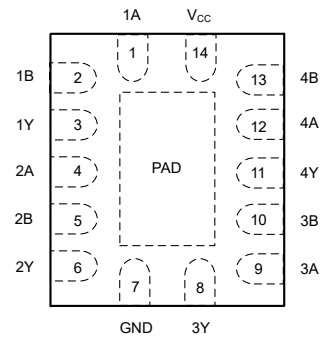


図 3-2. SN74LVC32A-Q1 BQA Package, 14-PIN WQFN (Top View)

表 3-1. Pin Functions

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
1A	1	I	Channel 1, Input A
1B	2	I	Channel 1, Input B
1Y	3	O	Channel 1, Output Y
2A	4	I	Channel 2, Input A
2B	5	I	Channel 2, Input B
2Y	6	O	Channel 2, Output Y
GND	7	—	Ground
3Y	8	O	Channel 3, Output Y
3A	9	I	Channel 3, Input A
3B	10	I	Channel 3, Input B
4Y	11	O	Channel 4, Output Y
4A	12	I	Channel 4, Input A
4B	13	I	Channel 4, Input B
V <sub>CC</sub>	14	—	Positive Supply
Thermal Information <sup>(2)</sup>		—	The thermal pad can be connected to GND or left floating. Do not connect to any other signal or supply.

(1) Signal Types: I = Input, O = Output, I/O = Input or Output, P = Power Supply, G = Ground.

(2) For BQA package only.

## 4 Specifications

### 4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	−0.5	6.5	V
V <sub>I</sub>	Input voltage range <sup>(1)</sup>	−0.5	6.5	V
V <sub>O</sub>	Output voltage range <sup>(1) (2)</sup>	−0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	−50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	−50	mA
I <sub>O</sub>	Continuous output current		±50	mA
	Continuous current through V <sub>CC</sub> or GND		±100	mA
T <sub>stg</sub>	Storage temperature range	−65	150	°C

(1) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(2) The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

### 4.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Human body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±2000	V
	Charged device model (CDM), per AEC Q100-011	±1000	V

(1) AEC Q100-002 indicates that HBM stressing must be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 4.3 Recommended Operating Conditions

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	Operating	2	3.6	V
		Data retention only	1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2.7V to 3.6V		2	V
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2.7V to 3.6V		0.8	V
V <sub>I</sub>	Input voltage	0	5.5	V	
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.7V	−12	mA	
		V <sub>CC</sub> = 3V	−24		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7V	12	mA	
		V <sub>CC</sub> = 3V	24		
Δt/Δv	Input transition rise or fall rate		7	ns/V	
T <sub>A</sub>	Operating free-air temperature	−40	125	°C	

### 4.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74LVC32A-Q1			UNIT
		BQA (WQFN)	D (SOIC)	PW (TSSOP)	
		14 PINS	14 PINS	14 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	102.3	86	150.8	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

## 4.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100μA	2.7V to 3.6V	V <sub>CC</sub> - 0.2		V	
	I <sub>OH</sub> = -12mA	2.7V	2.2			
		3V	2.4			
	I <sub>OH</sub> = -24mA	3V	2.2			
V <sub>OL</sub>	I <sub>OL</sub> = 100μA	2.7V to 3.6V			0.2	V
	I <sub>OL</sub> = 12mA	2.7V			0.4	
	I <sub>OL</sub> = 24mA	3V			0.55	
I <sub>I</sub>	V <sub>I</sub> = 5.5V or GND	3.6V			±5	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6V			10	μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6V, Other inputs at V <sub>CC</sub> or GND	2.7V to 3.6V			500	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3V			5	pF

(1) All typical values are at V<sub>CC</sub> = 3.3V, T<sub>A</sub> = 25°C.

## 4.6 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

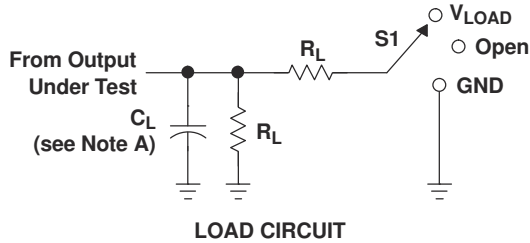
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.7V		V <sub>CC</sub> = 3.3V ± 0.3V		UNIT
			MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	4.4		1	3.8	ns

## 4.7 Operating Characteristics

T<sub>A</sub> = 25°C

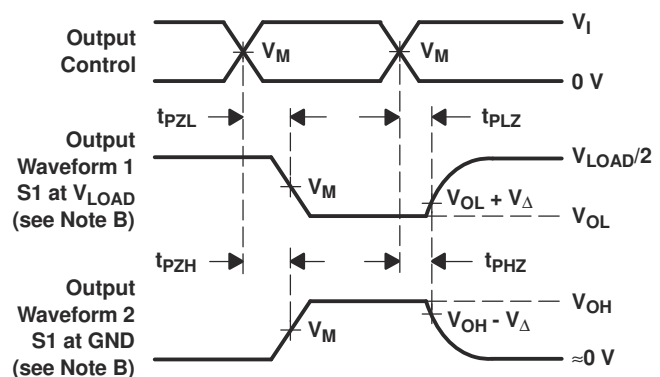
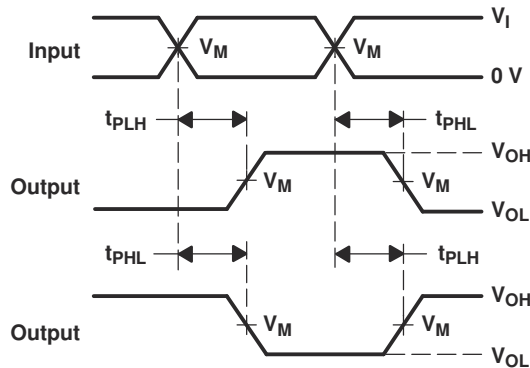
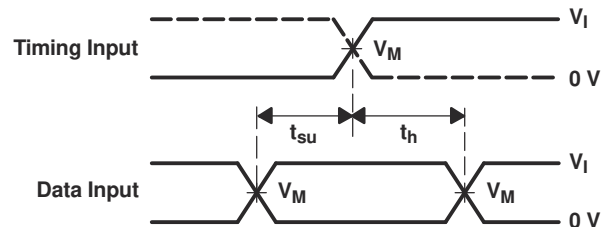
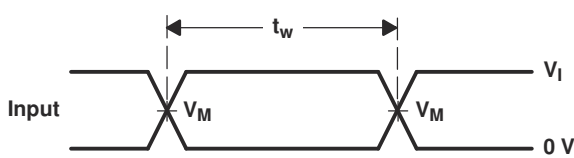
PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 2.5V	V <sub>CC</sub> = 3.3V	UNIT
		TYP	TYP	
C <sub>pd</sub> Power dissipation capacitance per gate	f = 10MHz	10.6	12.5	pF

## 5 Parameter Measurement Information



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
2.7 V	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

**图 5-1. Load Circuit and Voltage Waveforms**

## 6 Detailed Description

### 6.1 Overview

The device performs the Boolean function  $Y = A + B$  or  $Y = \overline{\overline{A} \cdot \overline{B}}$  in positive logic.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

### 6.2 Functional Block Diagram



図 6-1. Logic Diagram, Each Gate (Positive Logic)

### 6.3 Device Functional Modes

Function Table  
(Each Gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L

## 7 Application and Implementation

### 注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

### 7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- $\mu\text{F}$  capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu\text{F}$  and 1- $\mu\text{F}$  capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in given example layout image.

### 7.2 Layout

#### 7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must never be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

#### 7.2.2 Layout Example

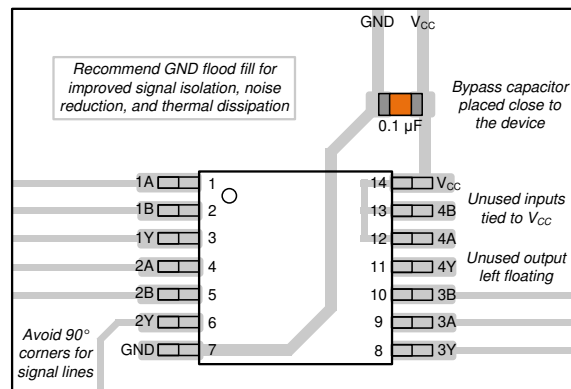


図 7-1. Example Layout for the SN74LVC32A-Q1



## 8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 8.1 Documentation Support (Analog)

#### 8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**表 8-1. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LVC32A-Q1	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 8.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[www.tij.co.jp](http://www.tij.co.jp) のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

### 8.3 サポート・リソース

[テキサス・インスツルメンツ E2E™ サポート・フォーラム](#) は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

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### 8.4 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.  
すべての商標は、それぞれの所有者に帰属します。

### 8.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

### 8.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

## 9 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision C (March 2024) to Revision D (May 2024)	Page
• Updated RθJA value: PW = 113 to 150.8, all values in °C/W .....	4

**Changes from Revision B (February 2008) to Revision C (March 2024)**
**Page**

- 「パッケージ情報」表、「ピンの機能」表、「ESD 定格」表、「熱に関する情報」表、「デバイスの機能モード」、「アプリケーションと実装」セクション、「デバイスおよびドキュメントのサポート」セクション、および「メカニカル、パッケージ、および注文情報」セクションを追加 ..... 1
- 「パッケージ情報」表、「ピン構成および機能」セクション、および「熱に関する情報」表に BQA パッケージを追加 ..... 1

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC32AQDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC32AQ	<a href="#">Samples</a>
SN74LVC32AQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC32AQ	<a href="#">Samples</a>
SN74LVC32AQPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC32AQ	<a href="#">Samples</a>
SN74LVC32AWBQARQ1	ACTIVE	WQFN	BQA	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC32Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74LVC32A-Q1 :**

- Catalog : [SN74LVC32A](#)
- Enhanced Product : [SN74LVC32A-EP](#)
- Military : [SN54LVC32A](#)

## NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC32AQPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC32AQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC32AWBQARQ1	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**




\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC32AQPWRG4Q1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LVC32AQPWRQ1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LVC32AWBQARQ1	WQFN	BQA	14	3000	210.0	185.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## GENERIC PACKAGE VIEW

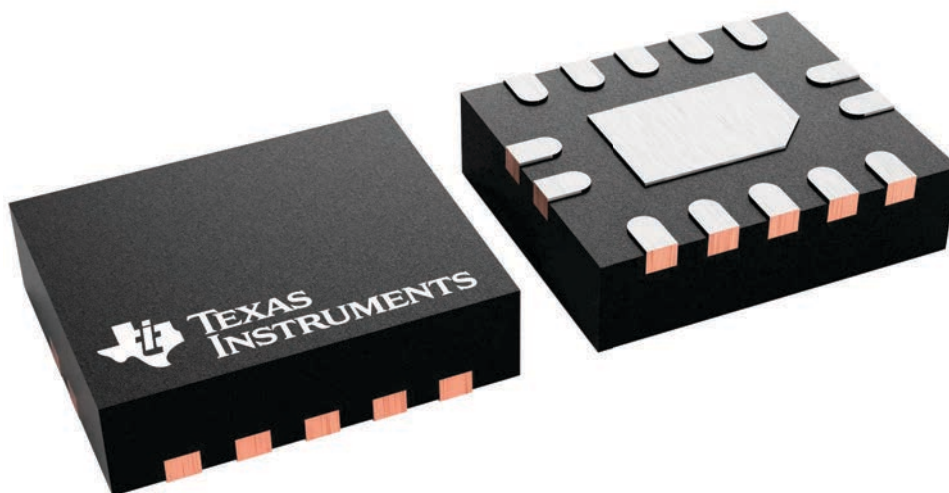
**BQA 14**

**WQFN - 0.8 mm max height**

2.5 x 3, 0.5 mm pitch

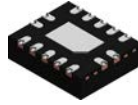
PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4227145/A

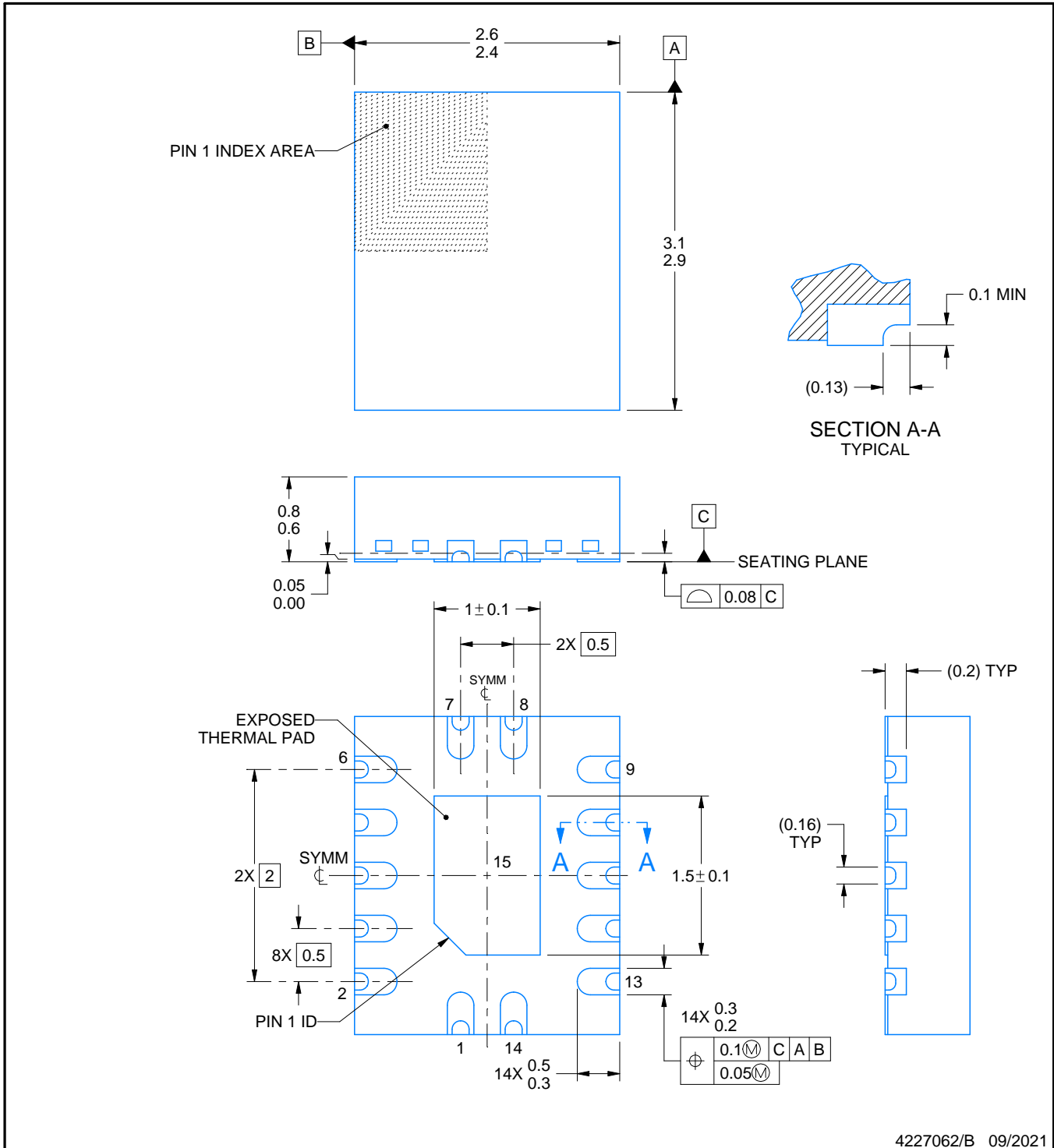
# BQA0014B



## PACKAGE OUTLINE

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



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### NOTES:

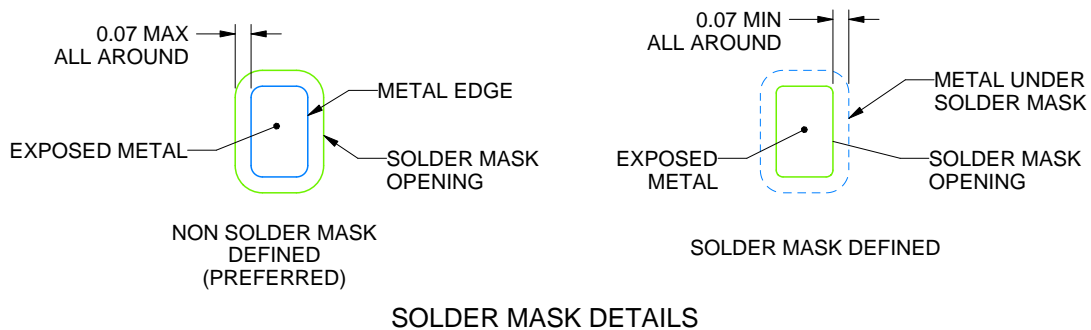
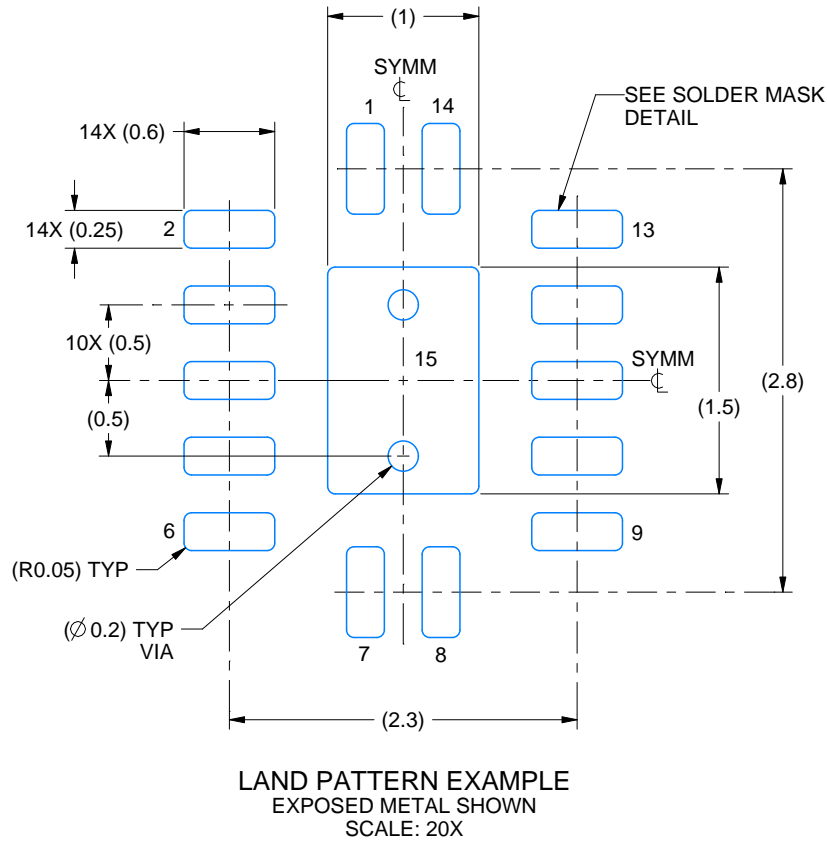
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

**BQA0014B**

**WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



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NOTES: (continued)

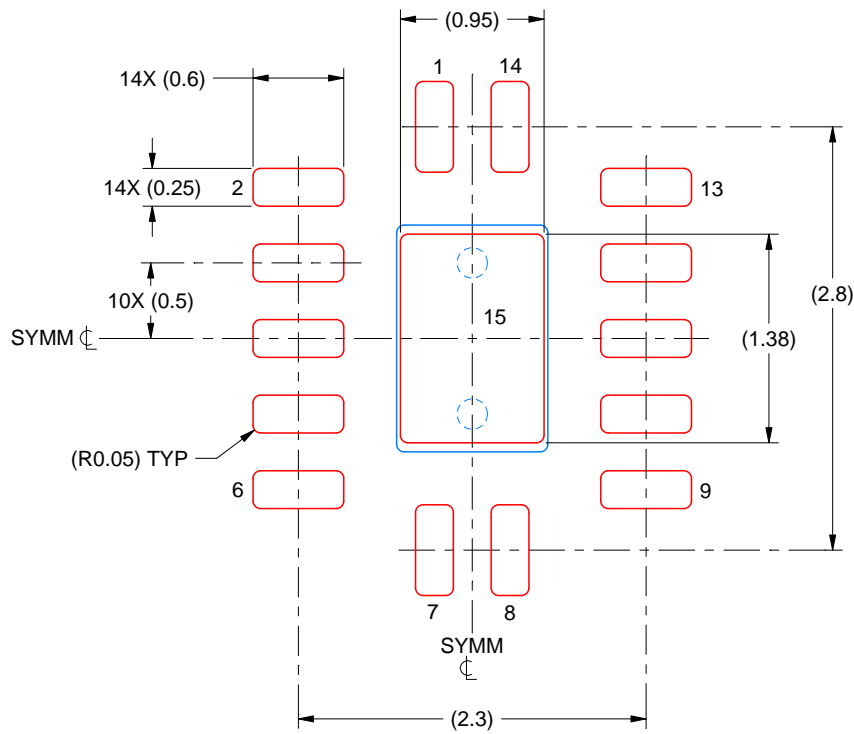
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

BQA0014B

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 MM THICK STENCIL  
SCALE: 20X

EXPOSED PAD 15  
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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